



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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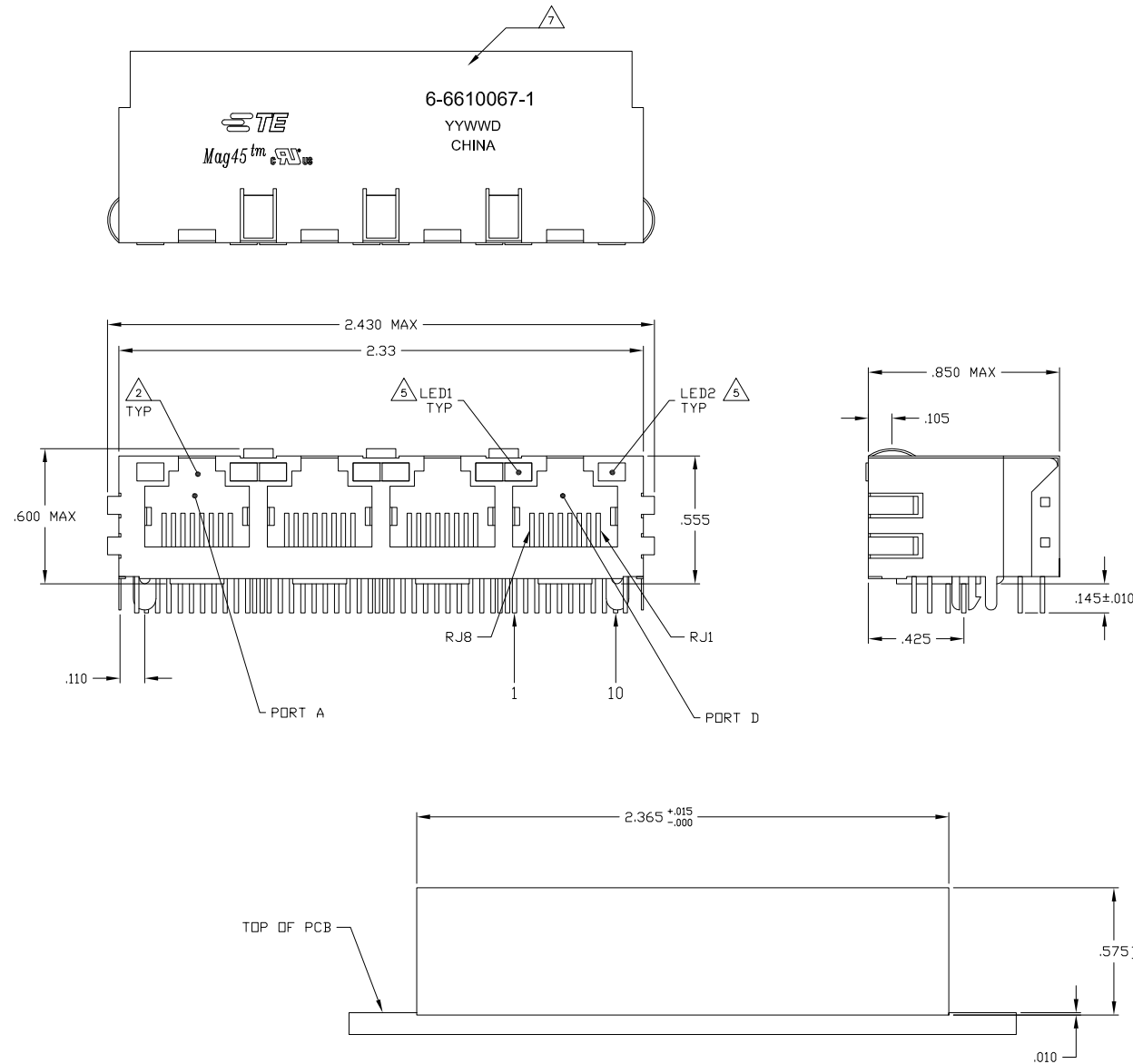
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LOC		REV		DATE		BY		APPD	
AA	22	B	REV PER	ECO-08-026409	02SEP2008	VL	TX		
		C	ECO-11-012433		20MAY2011	EL	LR		

MECHANICAL:



1. MATERIALS:
  - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
  - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL.
  - SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
  - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDERTAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
  - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
3. MAGNETICS
  - IMPEDANCE: 100 OHMS
  - TURNS RATIO (CHIP-CABLE): 1:1 ALL FOUR PAIRS
  - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100KHZ, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
  - ALL FOUR PAIRS BI-DIRECTIONAL
  - PERFORMANCE @ 25°C:
    - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
    - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
    - 12-20LOG(f/80)dB MIN FROM 4.0.1MHz TO 100MHz
    - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
    - 33-20\*LOG(f/50)dB MIN FROM 4.0.1MHz TO 100MHz
    - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
  - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
5. IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
  - LED COLOR : DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. ± VF=5V
  - FORWARD CURRENT (IF): GREEN 12 mA TYP. ± VF=5V
6. INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.
7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

1X4 SUGGESTED PANEL CUTOUT

GREEN	GREEN	6-6610067-1
LED1	LED2	PART NUMBER

DIMENSIONS:		REV		DATE		BY		APPD	
0 P.C.	± .	1	VARELA	17MAR2003	17MAR2003				
1 P.C.	± .	2	FAROLE	17MAR2003	17MAR2003				
2 P.C.	± .010	3	FAROLE	17MAR2003	17MAR2003				
3 P.C.	± .008	4	FAROLE	17MAR2003	17MAR2003				
4 P.C.	± .008								
ANGLES	± .								
MATERIAL	FINISH	WEIGHT							

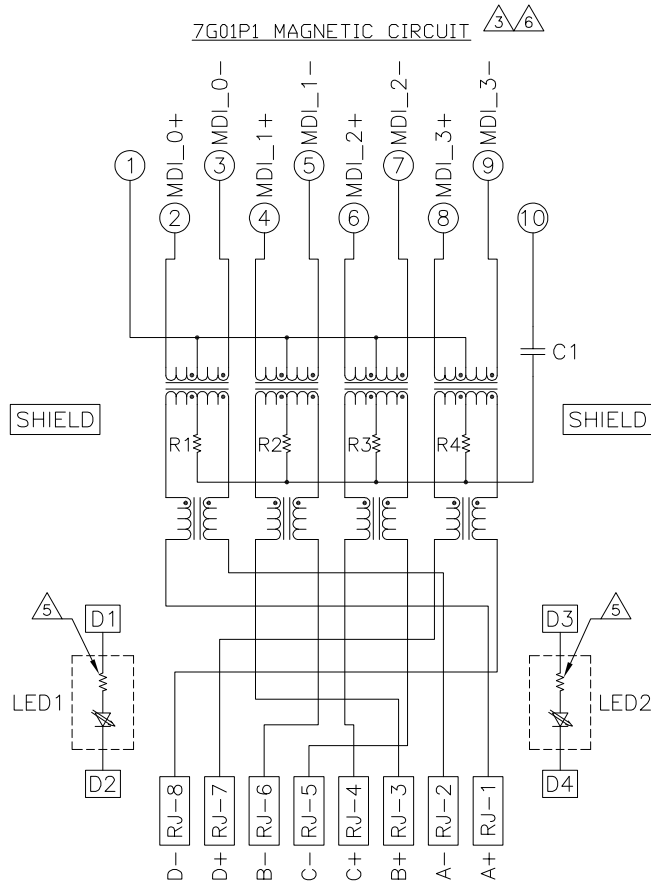
STE TE Connectivity

1X4 MAC45(TM) MODULAR JACK, 701P1 SCHEMATIC, (10 PIN HORIZONTAL), 7001P1 MAGNETIC CIRCUIT, DECOUPLING CAPACITOR, WITH RESISTOR LEADS

SIZE	DATE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C=6610067	

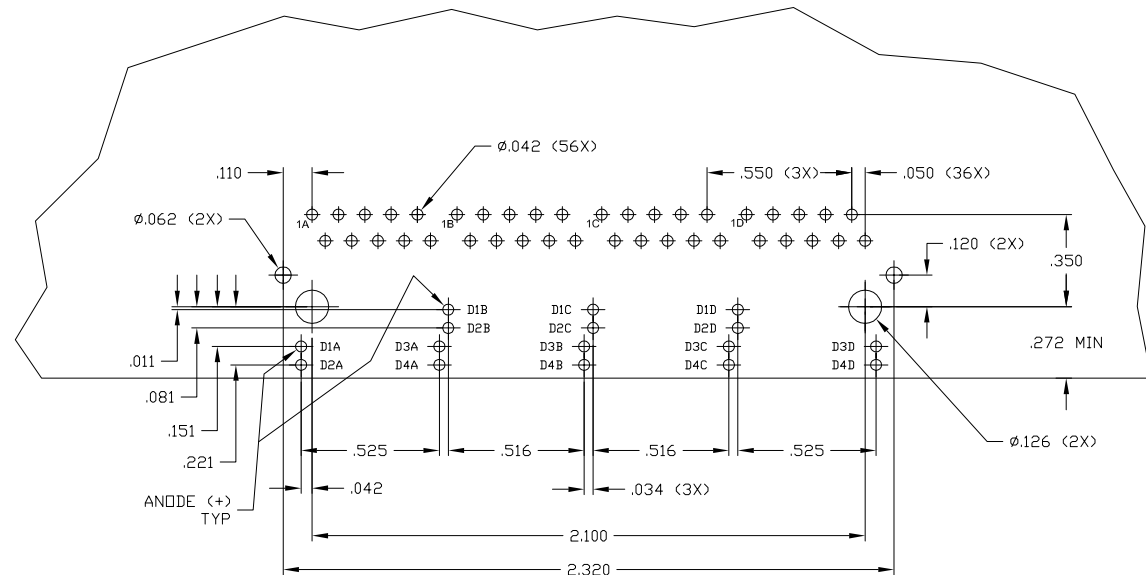
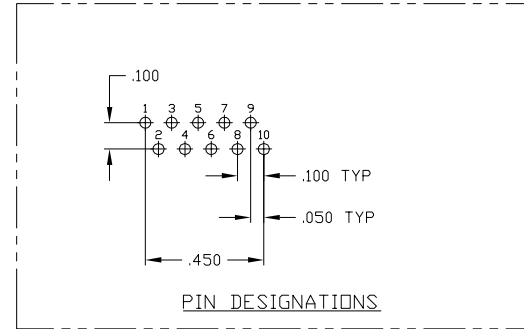
ELECTRICAL:

7G01P1 MAGNETIC CIRCUIT



C1 = 1000 pF, 2kV CAPACITOR

R1-R4 = 75 OHMS, 1/16W RESISTORS



SUGGESTED PCB LAYOUT  
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	1	DATE	17MAR2008	TE Connectivity
DRAWN BY: VARELA - 00000000		CHK	0	DATE	17MAR2008	
DESIGNED BY: FAROLE		APPD	0	DATE	17MAR2008	1X4 MAG45(TM) MODULAR JACK, 7G01P1 SCHEMATIC, (10 PIN HORIZONTAL), 7G01P1 MAGNETIC CIRCUIT, DECOUPLING CAPACITOR, WITH RESISTOR LEADS
DIMENSIONS: INCHES		PRODUCT SPEC	108-2100			
0 P.L.C ± .010		APPLICATION SPEC	108-2100			
1 P.L.C ± .008		SIZE	A1	00779	C=6610067	
2 P.L.C ± .005		WEIGHT	-			
3 P.L.C ± .005		MATERIAL	-			
4 P.L.C ± .005		FINISH	-			
MATERIAL		RESTRICTED TO	CUSTOMER DRAWING			
FINISH		SCALE	4:1			
WEIGHT		SHEET	2 of 2			
MATERIAL		REV	C			